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1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50 51 52

# TRANSMITTAL FORM



Electronic Version 1.0.3

Stylesheet Version: 1.0

Submission Type: Utility Patent  
Filing

Attorney Docket  
Number:

9223-US-  
PA

## FLIP-CHIP PACKAGE SUBSTRATE AND FLIP CHIP DIE

First Named Inventor: Mr. Chi-Hsing Hsu

### SUBMITTED BY

Name:	Dr. Belinda Lee
Registration Number:	46,863
Electronic Signature Mark: /Belinda Lee/	Date Signed: 20020802

*I certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.*

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### Attached Files:

declaration	9223declaration1.tif
declaration	9223declaration2.tif
specification	9233usf.xml
patent-assignments	9223usasgn.xml

fee-transmittal  
bibd-transmittal

9223usfee.xml  
9223usapds.xml

**Attached Image File(s):**

9223declaration1.tif  
9223declaration2.tif

Comments:

## COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## FLIP-CHIP PACKAGE SUBSTRATE AND FLIP CHIP DIE

the specification of which

☒ is attached hereto.

☐ was filed on \_\_\_\_\_

as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
91208321	Taiwan, R.O.C.	2002/6/5	X	

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

**Belinda Lee**

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**Belinda Lee**

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Chi-Hsing Hsu

Signature

Jun.25, 2002

Date

Sole or First Joint Inventor: **Chi-Hsing Hsu**

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# FEE TRANSMITTAL

Electronic Version 1.1.0

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*Patent fees are subject to annual revisions on or about October 1st of each year.*

Large Entity

**TOTAL FEES AUTHORIZED: \$ 900**

## BANK (CREDIT) CARD INFORMATION:

Credit Card Number: 3109  
Expiration Date: 20030430  
Authorized Name: LEE, HUAI-LU  
Billing Address: 99999

## BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	101	\$ 740

Subtotal For Basic Filing Fee: \$ 740

## EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 22	103	\$ 18	2	\$ 36
Independent Claims: 4	102	\$ 84	1	\$ 84

Subtotal For Extra Claims Fees: \$ 120

## ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	581	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40